

Amendments to the Specification

Please add the following section heading before the paragraph beginning "The invention relates to a method" at page 1, line 1:

BACKGROUND OF THE INVENTION

Please add the following section heading before the paragraph beginning "In accordance with a first aspect of the invention" at page 3, line 23:

BRIEF SUMMARY OF THE INVENTION

Please add the following section heading before the paragraph beginning "Figure 1 is a cross sectional view" at page 6, line 1:

BRIEF DESCRIPTION OF THE SEVERAL VIEWS OF THE DRAWINGS

Please add the following section heading after the paragraph beginning "Figure 4 is a cross sectional view" at page 6, line 15:

DETAILED DESCRIPTION OF THE INVENTION

Please add the following section heading and paragraph after the claims and on new page 15:

ABSTRACT

A method of assembling a semiconductor device package includes first attaching a semiconductor device to a die-pad area of a leadframe. Electrical connections are then between electrical contact areas on the semiconductor device and electrical connection areas on the

leadframe to form a device/leadframe assembly. An adhesion enhancing coating is then deposited on the exposed surface of the device frame/leadframe assembly before encapsulating the coated device leadframe assembly in an electrically insulating material.